



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE75080-ESH	Issued	12. August 2021
MA#	MA005595725		
Package	PG-TSDSO-24-21	Weight*	111.95 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.094	2.76	2.76	27635	27635
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		141	
	non noble metal	zinc	7440-66-6	0.063	0.06		565	
	non noble metal	iron	7439-89-6	1.266	1.13		11306	
	non noble metal	copper	7440-50-8	51.392	45.92	47.12	459075	471087
wire	non noble metal	copper	7440-50-8	0.759	0.68	0.68	6777	6777
encapsulation	organic material	carbon black	1333-86-4	0.151	0.13		1344	
	plastics	epoxy resin	-	5.870	5.24		52435	
	inorganic material	silicondioxide	60676-86-0	44.150	39.44	44.81	394385	448164
leadfinish	non noble metal	tin	7440-31-5	2.820	2.52	2.52	25191	25191
plating	noble metal	silver	7440-22-4	1.279	1.14	1.14	11425	11425
glue	plastics	epoxy resin	-	0.190	0.17		1701	
	noble metal	silver	7440-22-4	0.898	0.80	0.97	8020	9721
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com